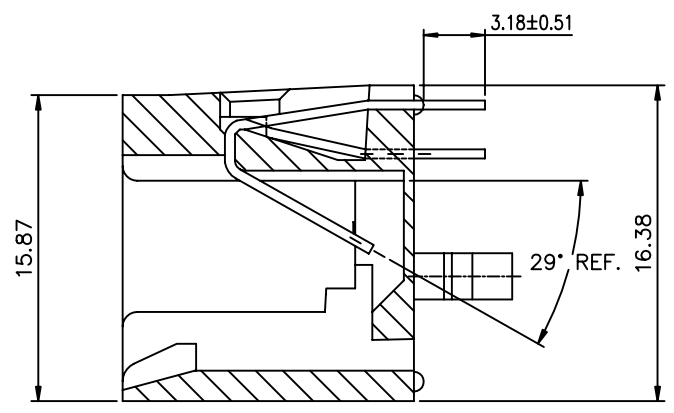
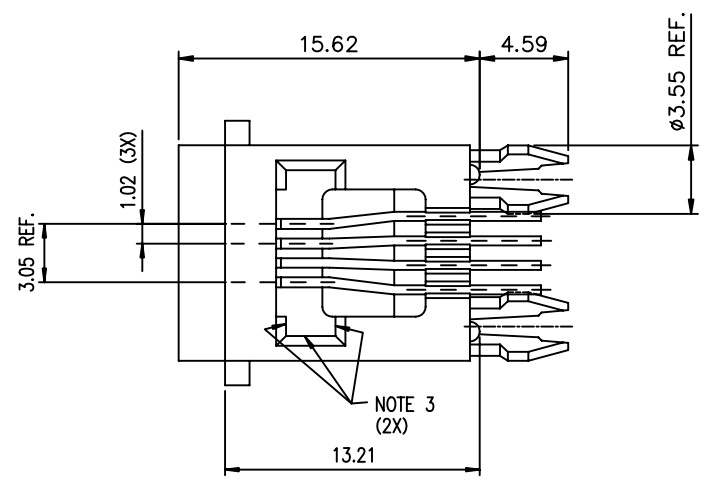
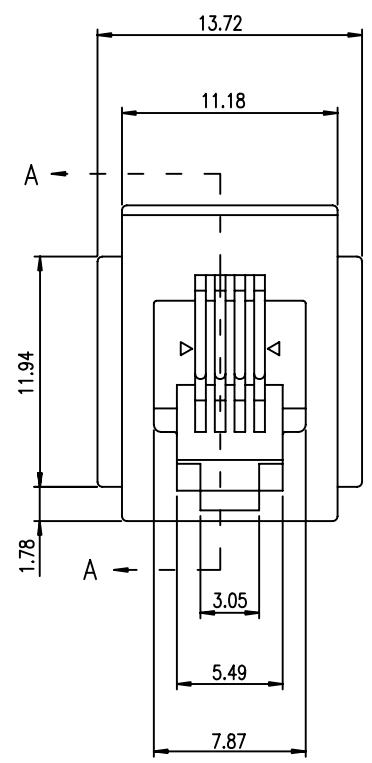


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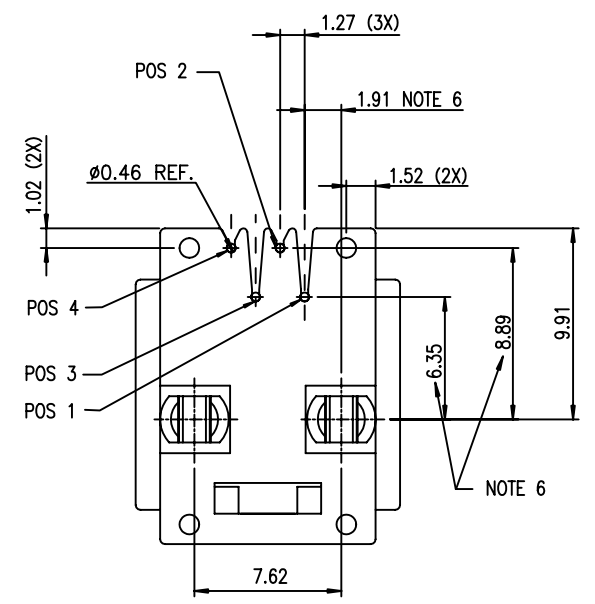
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PRODUCT NO.
SEE TABLE



SECTION A-A



mat'l code		tolerance unless otherwise specified		CUSTOMER COPY		 www.fcconnect.com	
rev.	ecn no.	dr	date	linear	.0 ± 0.25	projection	title
A	T80030	CAW/L	01/21/98				
B	T90021	M/W	01/19/99	angles	.00 ± 0.13		4 POS VERT. SPECIAL PEG P.C.B. III MOD JACK ASSY
C	N10059	WL	05/22/01				
D	N04-0023	D QIN	06/07/04	dr	C L FENG	02/21/97	unit
E	N04-0102	YS	11/23/04	enrg	TONY CHIEN	02/21/97	mm/inch
F	N04-0109	YS	11/30/04	chr	TONY CHIEN	02/21/97	scale
G	N08-0097	SH	09/24/06	appd	JENN TSAO	02/21/97	product family MOD JACK
sheet		revision	G	G	size		dwg no.
index		sheet	1	2	A3		61835
							code TWN
							sheet 1 OF 2

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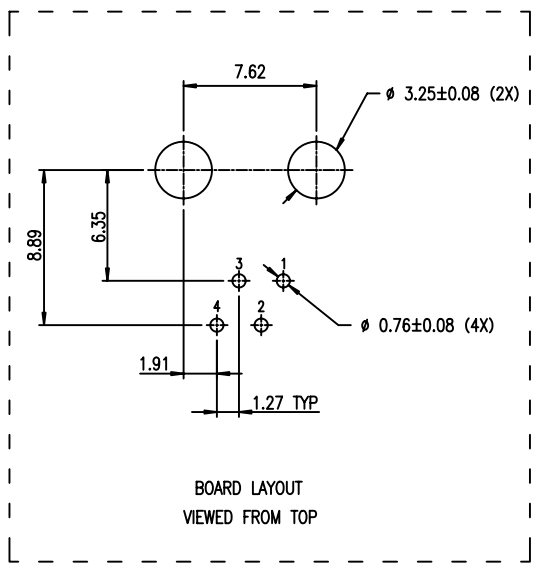


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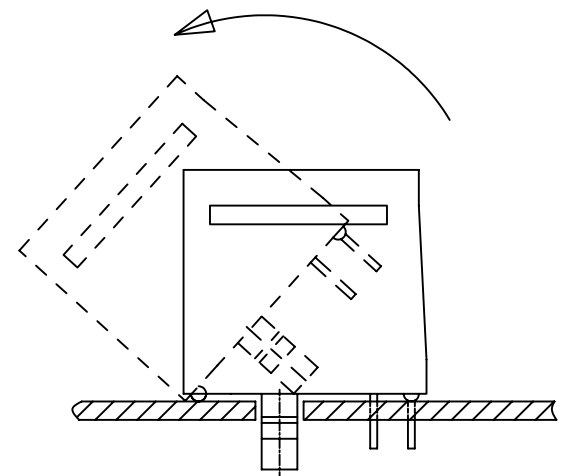
PRODUCT NO.	NO. OF POS	LOADED POS	HSG COLOR
61835-X441	4	ALL POS	BLACK
-X421	4	3,4	BLACK
-X442	4	ALL POS	GRAY
-X422	4	3,4	GRAY

PLATING CODE X	PLATING
0	30 μ" G.X.T.
1	15 μ" GOLD
3	30 μ" GOLD
4	6 μ" GOLD
5	50 μ" GOLD

⑩
⑩



DIRECTION OF DISMOUNT



JACK DISMOUNT METHOD

DETAIL A
NOTE 5

NOTES:

- P/N WITH DASH X4XX -NORMAL WAVE SOLDERING APPLICATION.
- PACKAGING SPEC. GES-14-351. (USING TRAY).
- SCRATCH MARKS ACCEPTABLE ON THESE SURFACES.
- JACK IS FOR 1.57/.062 THICK PCB.
- SHOULD THE JACK NEED TO BE DISMOUNTED FROM THE PCB. PLS REMOVE JACK AS PER RECOMMENDED METHOD HEREIN. (DETAIL A) NIPPING THE LEGS OF THE PEG TOGETHER IS DISALLOWED, OTHERWISE LEG BREAKAGE MAY OCCUR.
- THESE DIMENSIONS ARE MEASURED FROM THE TOP OF THE PEG.
- THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
- IF LF P/N PACKSGING MEETS GS-14-920 SPECIFICATION
- THE HOUSING WILL WITHSTAND EXPOSURE TO 260° PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.57mm MINIMUM THICK CIRCUIT BOARD
- ⑩ EQUIVALENT THICKNESS Au AND GXT PLATING HAVE SAME FUNCTION AND THEY ARE ALTERNATIVE BY THE CUSTOEMR .

mat'l code		tolerance unless otherwise specified		CUSTOMER COPY		 www.fciconnect.com	
rev.	ecn no.	dr	date	linear	.0 ± 0.25	projection	
G					.00 ± 0.13		
				angles	± 2°		
				dr	C L FENG 02/20/97	unit	product family MOD JACK
				engr	TONY CHIEN 02/20/97	mm/inch	code TWN
				chr	TONY CHIEN 02/20/97	scale	size A3
				appd	JENN TSAO 02/20/97		dwg no. 61835
							sheet 2 OF
sheet	revision						
index	sheet						